

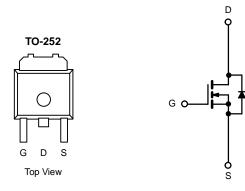
# FR3518-VB Datasheet N-Channel 100-V (D-S) MOSFET

| PRODUCT SUMMARY          |                                  |                    |  |  |
|--------------------------|----------------------------------|--------------------|--|--|
| V <sub>(BR)DSS</sub> (V) | r <sub>DS(on)</sub> (Ω)          | I <sub>D</sub> (A) |  |  |
| 100                      | 0.030 at V <sub>GS</sub> = 10 V  | 40                 |  |  |
|                          | 0.035 at V <sub>GS</sub> = 4.5 V | 37                 |  |  |

#### **FEATURES**

- Trench Power MOSFETS
- 175 °C Junction Temperature
- Low Thermal Resistance Package





N-Channel MOSFET

| <b>ABSOLUTE MAXIMUM RATINGS</b> $T_C = 25  ^{\circ}C$ , unless otherwise noted |                                     |                                   |                  |      |  |
|--|-------------------------------------|-----------------------------------|------------------|------|--|
| Parameter  | -                                   | Symbol                            | Limit            | Unit |  |
| Drain-Source Voltage   |                                     | V <sub>DS</sub>                   | 100              | V    |  |
| Gate-Source Voltage  | V <sub>GS</sub>                     | ± 20                              | v                |      |  |
| Continuous Drain Current (T <sub>.1</sub> = 175 °C)                            | T <sub>C</sub> = 25 °C              | I-                                | 40               |      |  |
| Continuous Diam Current (1) = 175 C)   | T <sub>C</sub> = 125 °C             | I <sub>D</sub>                    | 23               |      |  |
| Pulsed Drain Current   |                                     | I <sub>DM</sub>                   | 120              | A    |  |
| Avalanche Current  |                                     | I <sub>AR</sub>                   | 35               |      |  |
| Repetitive Avalanche Energy <sup>a</sup>                                       | L = 0.1 mH                          | E <sub>AR</sub>                   | 61               | mJ   |  |
|  | T <sub>C</sub> = 25 °C              | В                                 | 107 <sup>b</sup> | 14/  |  |
| Maximum Power Dissipation <sup>a</sup>   | T <sub>A</sub> = 25 °C <sup>c</sup> | P <sub>D</sub>                    | 3.75             | W    |  |
| Operating Junction and Storage Temperature Ra                                  | nge                                 | T <sub>J</sub> , T <sub>stg</sub> | - 55 to 175      | °C   |  |

| THERMAL RESISTANCE RATINGS |                          |                   |       |        |  |  |
|----------------------------|--------------------------|-------------------|-------|--------|--|--|
| Parameter                  |                          | Symbol            | Limit | Unit   |  |  |
| Junction-to-Ambient        | (PCB Mount) <sup>c</sup> | R <sub>thJA</sub> | 40    | °C/W   |  |  |
| Junction-to-Case (Drain)   |                          | R <sub>thJC</sub> | 1.4   | C/ V V |  |  |

#### Notes:

- a. Duty cycle  $\leq$  1 %.
- b. See SOA curve for voltage derating.
- c. When Mounted on 1" square PCB (FR-4 material).

<sup>\*</sup> Pb containing terminations are not RoHS compliant, exemptions may apply.



| Parameter                                     | Symbol               | Test Conditions   | Min. | Тур.  | Max.  | Unit |  |
|---|----------------------|---|------|-------|-------|------|--|
| Static  |                      |   |      |       |       |      |  |
| Drain-Source Breakdown Voltage                | V <sub>(BR)DSS</sub> | $V_{SS} = 0 \text{ V}, I_D = 250 \mu\text{A}$                           | 100  |       |       |      |  |
| Gate-Threshold Voltage                        | V <sub>GS(th)</sub>  | $V_{DS} = V_{GS}, I_D = 250 \mu A$                                      | 1    |       | 3     | v    |  |
| Gate-Body Leakage                             | I <sub>GSS</sub>     | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$                       |      |       | ± 100 | nA   |  |
|   |                      | V <sub>DS</sub> = 100 ,W <sub>GS</sub> = 0 V                            |      |       | 1     | μА   |  |
| Zero Gate Voltage Drain Current               | I <sub>DSS</sub>     | V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C |      |       | 50    |      |  |
|   |                      | V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C |      |       | 250   | 1    |  |
| On-State Drain Current <sup>a</sup>           | I <sub>D(on)</sub>   | $V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$                         | 75   |       |       | Α    |  |
|   |                      | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 5 A                            |      | 0.030 |       | Ω    |  |
|   |                      | $V_{GS} = 4.5 \text{ V}, I_D = 3 \text{ A}$                             |      | 0.035 |       |      |  |
| Drain-Source On-State Resistance <sup>a</sup> | r <sub>DS(on)</sub>  | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 5 A, T <sub>J</sub> = 125 °C   |      | 0.053 |       |      |  |
|   |                      | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3 A, T <sub>J</sub> = 175 °C   |      | 0.067 |       |      |  |
| Forward Transconductance <sup>a</sup>         | 9 <sub>fs</sub>      | V <sub>DS</sub> = 15 V, I <sub>D</sub> = 15 A                           | 10   |       |       | S    |  |
| Dynamic <sup>b</sup>                          | <b>.</b>             |   |      |       |       |      |  |
| Input Capacitance                             | C <sub>iss</sub>     |   |      | 2600  |       | pF   |  |
| Output Capacitance                            | C <sub>oss</sub>     | V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1 MHz                |      | 290   |       |      |  |
| Reverse Transfer Capacitance                  | C <sub>rss</sub>     |   |      | 120   |       |      |  |
| Total Gate Charge <sup>c</sup>                | Qg                   |   |      | 35    | 60    | nC   |  |
| Gate-Source Charge <sup>c</sup>               | Q <sub>gs</sub>      | $V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 40 \text{ A}$    |      | 11    |       |      |  |
| Gate-Drain Charge <sup>c</sup>                | Q <sub>gd</sub>      |   |      | 9     |       |      |  |
| Gate Resistance                               | R <sub>G</sub>       |   |      | 1.7   |       | Ω    |  |
| Turn-On Delay Time <sup>c</sup>               | t <sub>d(on)</sub>   |   |      | 11    | 20    |      |  |
| Rise Time <sup>c</sup>                        | t <sub>r</sub>       | $V_{DD} = 50 \text{ V, R}_{L} = 1.25 \Omega$                            |      | 12    | 20    | ns   |  |
| Turn-Off Delay Time <sup>c</sup>              | t <sub>d(off)</sub>  | $I_D \cong 40 \text{ A}, V_{GEN} = 10 \text{ V}, R_G = 2.5 \Omega$      |      | 30    | 45    |      |  |
| Fall Time <sup>c</sup>                        | t <sub>f</sub>       |   |      | 12    | 20    |      |  |
| Source-Drain Diode Ratings and Cha            | racteristics         | <sub>C</sub> = 25 °C <sup>b</sup>                                       |      |       |       |      |  |
| Continuous Current                            | Is                   |   |      |       | 40    |      |  |
| Pulsed Current                                | I <sub>SM</sub>      |   |      |       | 120   | Α    |  |
| Forward Voltage <sup>a</sup>                  | V <sub>SD</sub>      | I <sub>F</sub> = 30 A, V <sub>GS</sub> = 0 V                            |      | 1.0   | 1.5   | V    |  |
| Reverse Recovery Time                         | t <sub>rr</sub>      |   |      | 60    | 100   | ns   |  |
| Peak Reverse Recovery Current                 | I <sub>RM(REC)</sub> | $I_F = 30 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$         |      | 5     | 8     | Α    |  |
| Reverse Recovery Charge                       | Q <sub>rr</sub>      | ·   |      | 0.15  | 0.4   | μC   |  |

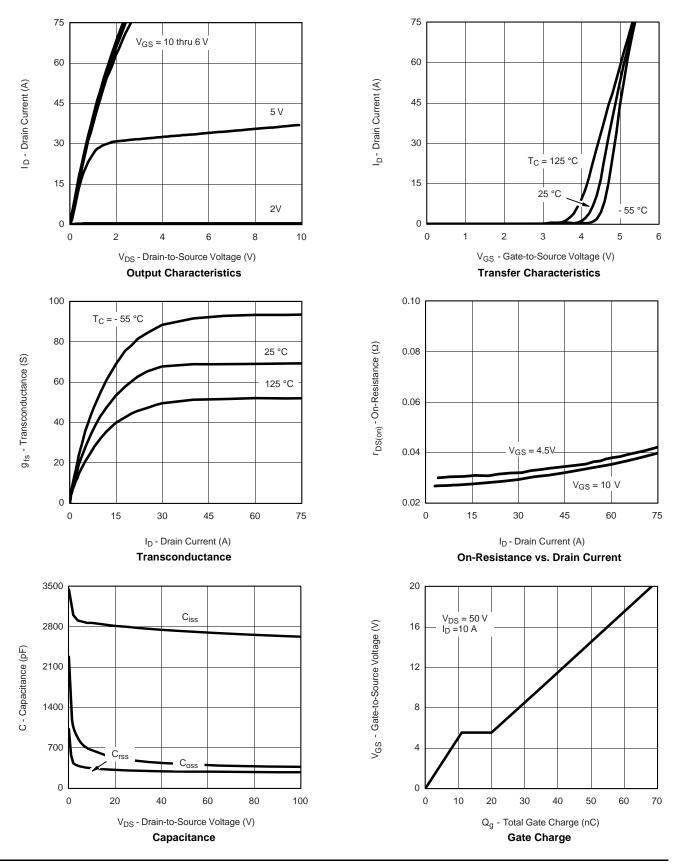
#### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

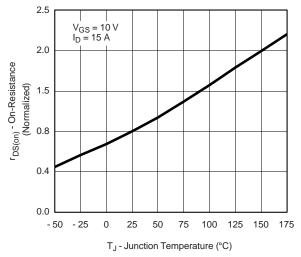


## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

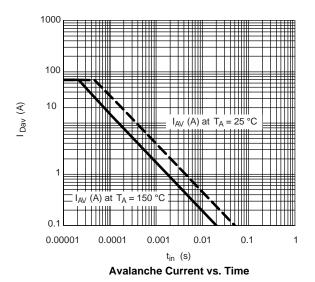




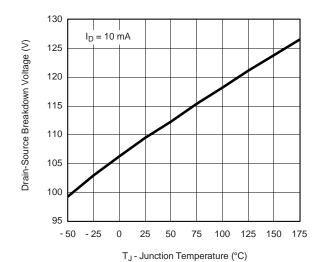
### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



On-Resistance vs. Junction Temperature



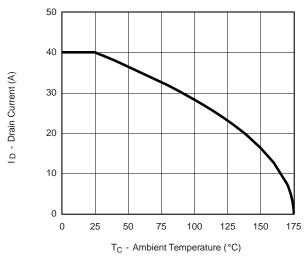
Source-Drain Diode Forward Voltage



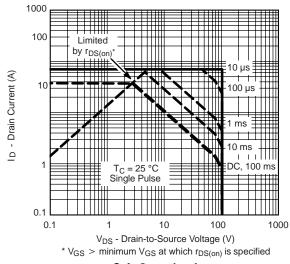
Drain-Source Breakdown Voltage vs. Junction Temperature



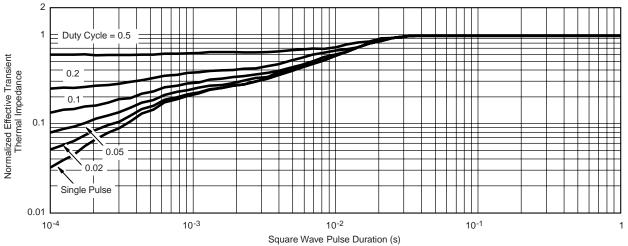
#### THERMAL RATINGS



Maximum Avalanche and Drain Current vs. Case Temperature



Safe Operating Area



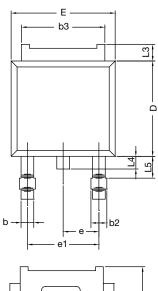
Normalized Thermal Transient Impedance, Junction-to-Case

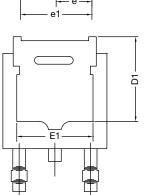
服务热线:400-655-8788

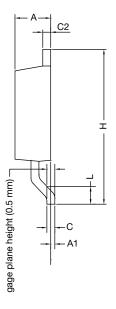
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# **TO-252AA CASE OUTLINE**







|                                 | MILLIMETERS |       | INC       | HES   |  |  |
|---------------------------------|-------------|-------|-----------|-------|--|--|
| DIM.                            | MIN.        | MAX.  | MIN.      | MAX.  |  |  |
| Α                               | 2.18        | 2.38  | 0.086     | 0.094 |  |  |
| A1                              | -           | 0.127 | -         | 0.005 |  |  |
| b                               | 0.64        | 0.88  | 0.025     | 0.035 |  |  |
| b2                              | 0.76        | 1.14  | 0.030     | 0.045 |  |  |
| b3                              | 4.95        | 5.46  | 0.195     | 0.215 |  |  |
| С                               | 0.46        | 0.61  | 0.018     | 0.024 |  |  |
| C2                              | 0.46        | 0.89  | 0.018     | 0.035 |  |  |
| D                               | 5.97        | 6.22  | 0.235     | 0.245 |  |  |
| D1                              | 5.21        | -     | 0.205     | -     |  |  |
| Е                               | 6.35        | 6.73  | 0.250     | 0.265 |  |  |
| E1                              | 4.32        | =     | 0.170     | -     |  |  |
| Н                               | 9.40        | 10.41 | 0.370     | 0.410 |  |  |
| е                               | 2.28 BSC    |       | 0.090     | BSC   |  |  |
| e1                              | 4.56 BSC    |       | 0.180 BSC |       |  |  |
| L                               | 1.40        | 1.78  | 0.055     | 0.070 |  |  |
| L3                              | 0.89        | 1.27  | 0.035     | 0.050 |  |  |
| L4                              | -           | 1.02  | -         | 0.040 |  |  |
| L5                              | 1.14        | 1.52  | 0.045     | 0.060 |  |  |
| ECN: X12-0247-Rev. M, 24-Dec-12 |             |       |           |       |  |  |

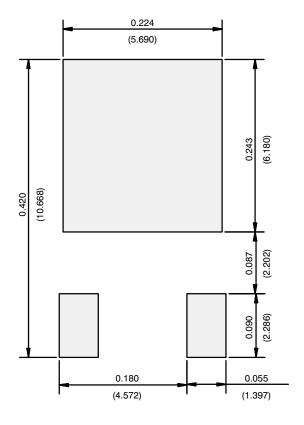
## DWG: 5347

Note

• Dimension L3 is for reference only.



## **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)



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